

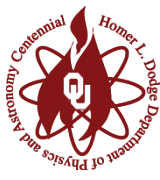


Presentation on:
Photoluminescence study of the defect-
induced recombination in $\text{Cu}(\text{In},\text{Ga})\text{Se}_2$ solar
cell

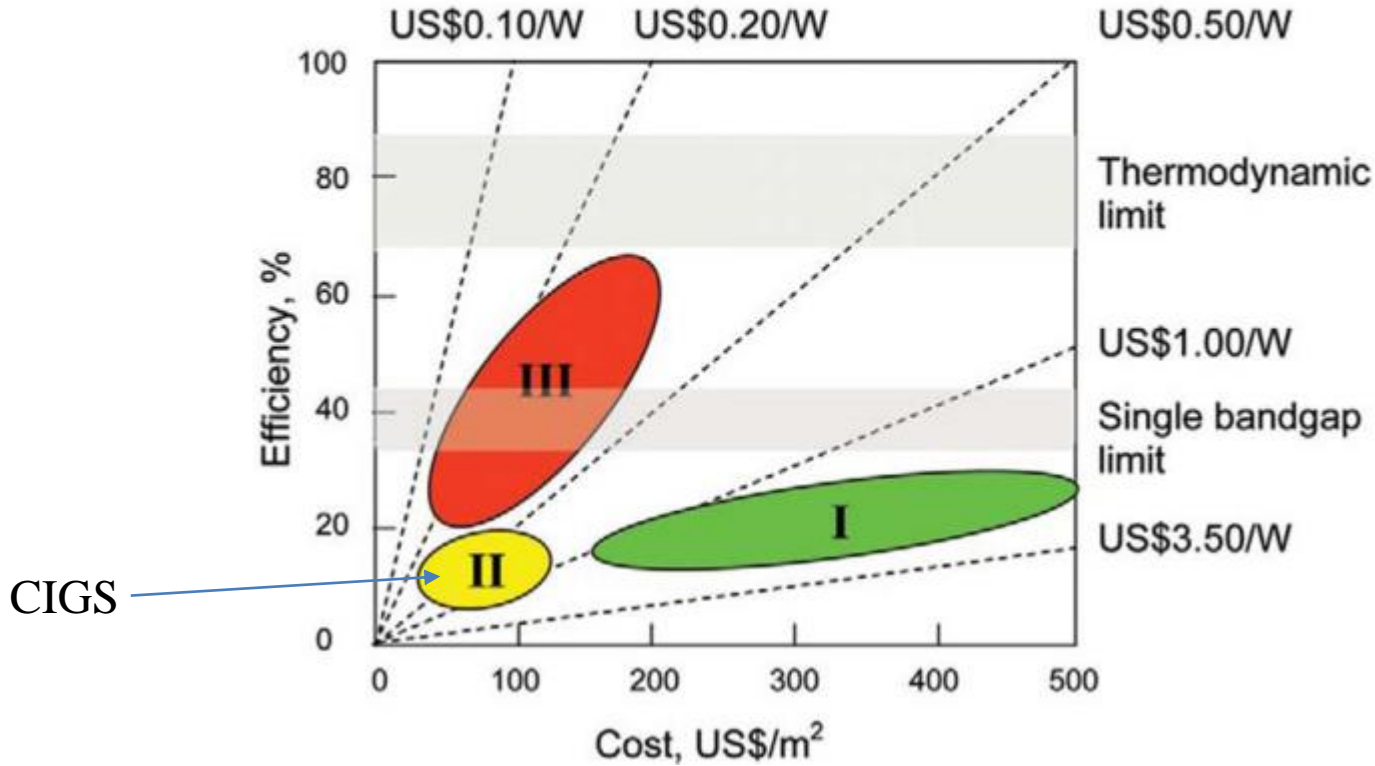
Collin Brown

Condensed Matter Journal Club

February 14th, 2017



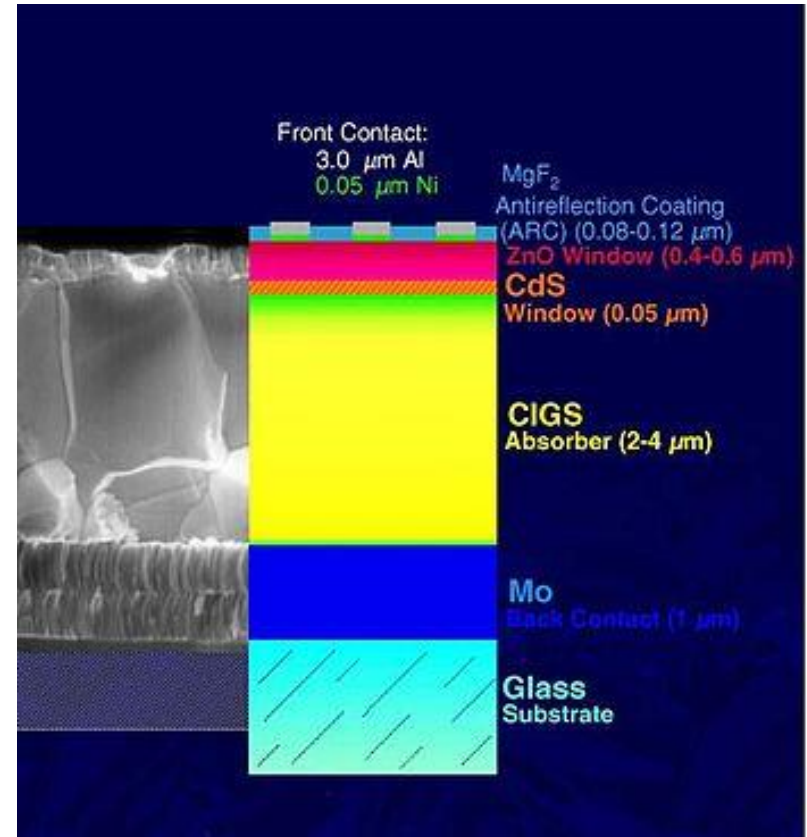
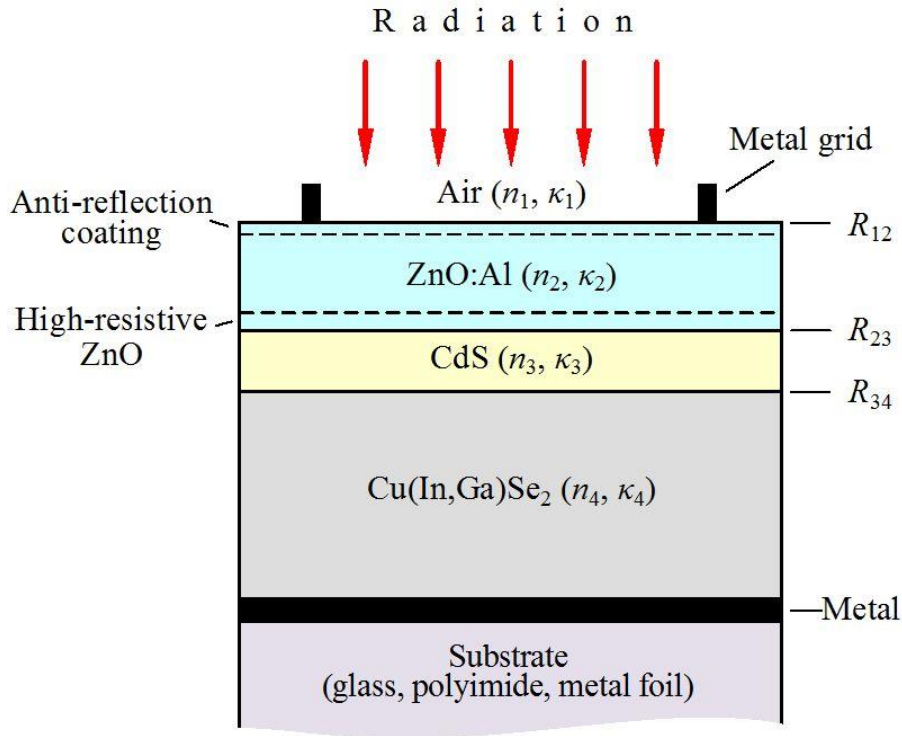
Tinted areas:
67 - 87% representing thermodynamic limit
31 - 41% representing single bandgap limit



G. Conibeer, 2007 *Third-generation photovoltaics* *Material Today* 10 11 44 50



$Cu(In, Ga)Se_2$ Solar Cells



Leonid A. Kosyachenko, *A Theoretical Description of Thin-Film $Cu(In, Ga)Se_2$ Solar Cell Performance.* (2015).

L. Kazmerski, NREL, 2005



Sputtering for deposition

Hybrid Method

Growth Process:

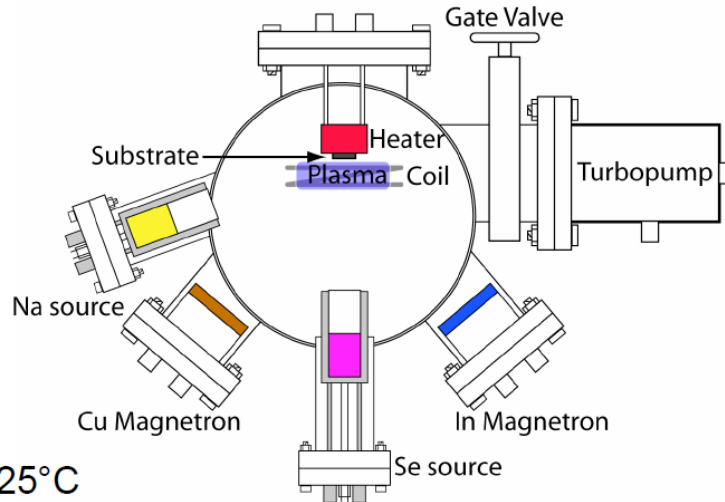
- Similar to MBE
- Evaporate Se
- Sputter metals
- Optional rf coil for ionization

Growth rate $\sim 1\mu\text{m/hr}$.
 Substrate temperature: $550\text{-}725^\circ\text{C}$

Cu-Ga target for Cu(In,Ga)Se_2

Cu target for pure CuInSe_2

Cu and Ga targets for CuGaSe_2



Epitaxy on GaAs:

Typical hole mobility
 $\sim 280\text{ cm}^2/\text{V}\cdot\text{sec}$

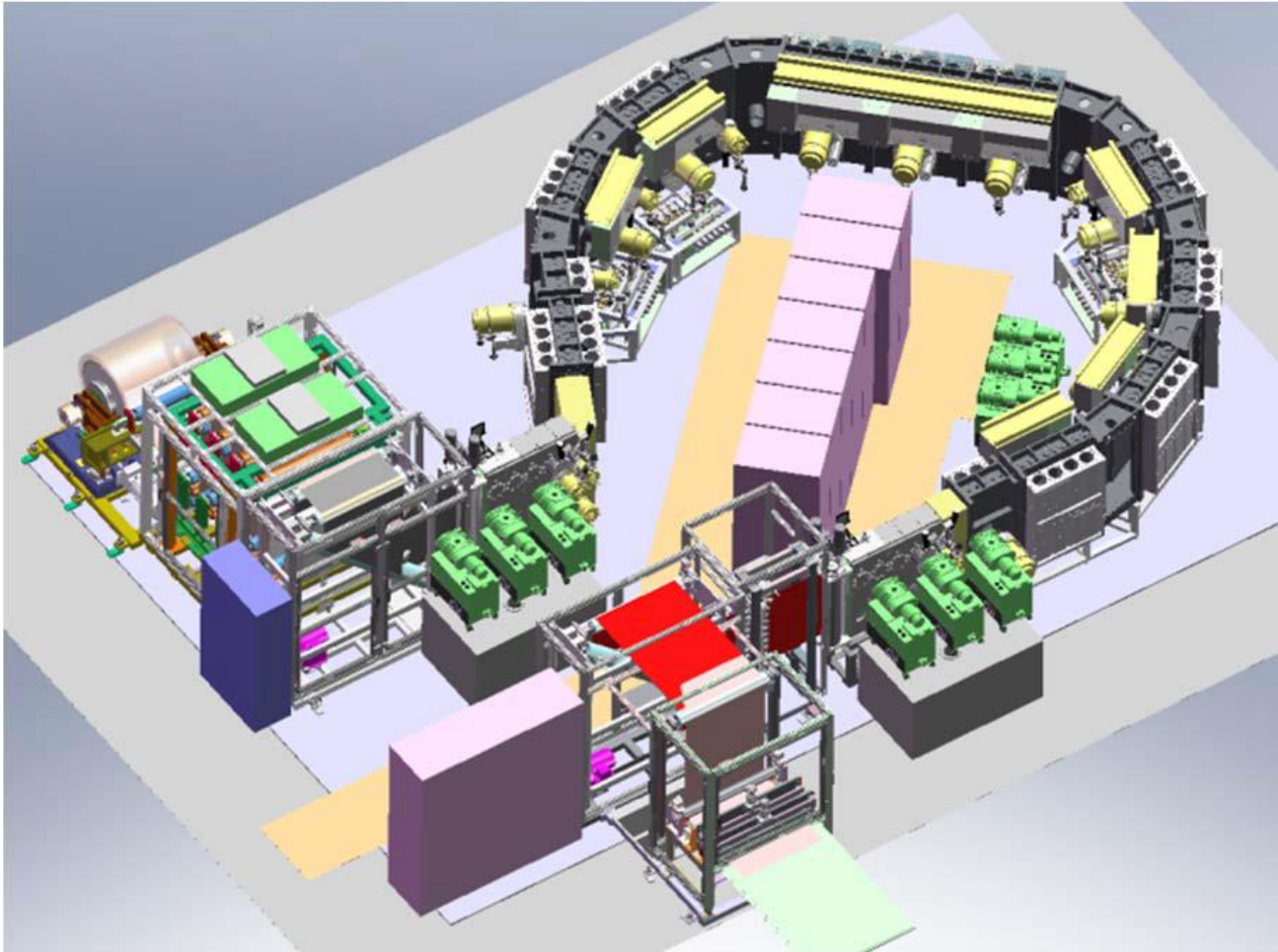
Typ. Carrier Lifetime:
 $\sim 0.4\text{ nsec}$



Image Credit: Angus Rockett



MiaSole



High throughput – All PVD process built on a roll of stainless steel

Image Credit: MiaSole

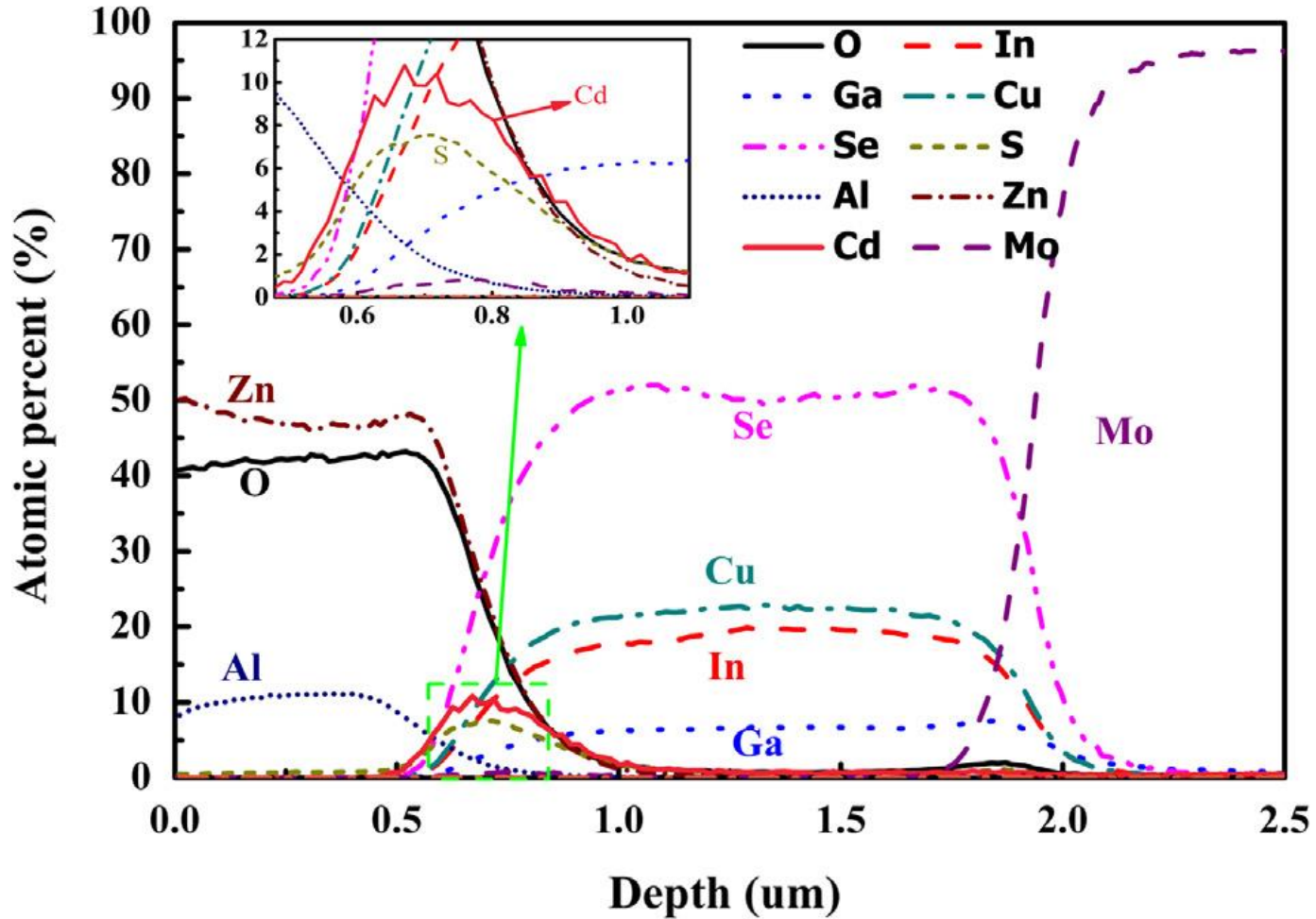


Experimental details

- CIGS samples deposited on soda lime glass (SLG) substrates by a 2 step sputtering process
- H_2Se in the second step for Selenization
- CdS layer by chemical bath deposition
- Other layers by Sputtering
- Annealed in N_2 gas ambient for 30s, with heating rate of $50^\circ\text{C}/\text{s}$
- SIMS to obtain compositional profile
- For PL, sample excited using 405 nm with 20 mW



Sims results





J-V curve results

Table 1
Comparison of parameters (conversion efficiency Eff , open-circuit voltage V_{oc} , short-circuit current density J_{sc} , fill factor FF , series resistance R_s , the reciprocal of the shunt resistance G , the diode ideality factor A and the dark saturated current density J_0) extracted from J - V analysis of as-deposited and RTA-treated CIGS solar cells.

Samples	Eff (%)	V_{oc} (V)	J_{sc} (mA/cm ²)	FF (%)	R_s (Ω cm ²)	G (ms/cm ²)	A	J_0 (mA/cm ²)
as-deposited	8.1 ± 0.1	0.56 ± 0.01	26.9 ± 0.1	54 ± 1	1.5	5.0	3.6	1.1×10^{-1}
150 °C RTA	8.2 ± 0.1	0.57 ± 0.01	27.8 ± 0.1	52 ± 1	1.9	3.8	3.7	1.7×10^{-2}
200 °C RTA	8.9 ± 0.1	0.58 ± 0.01	27.4 ± 0.1	56 ± 1	2.0	3.0	3.3	7.5×10^{-3}
300 °C RTA	11.4 ± 0.1	0.63 ± 0.01	29.2 ± 0.1	62 ± 1	0.9	2.1	2.8	2.1×10^{-5}
400 °C RTA	11.6 ± 0.1	0.59 ± 0.01	31.4 ± 0.1	63 ± 1	0.7	2.4	2.9	1.3×10^{-3}
500 °C RTA	3.6 ± 0.1	0.39 ± 0.01	27.9 ± 0.1	33 ± 1	1.1	5.1	9.7	1.6×10^{-2}

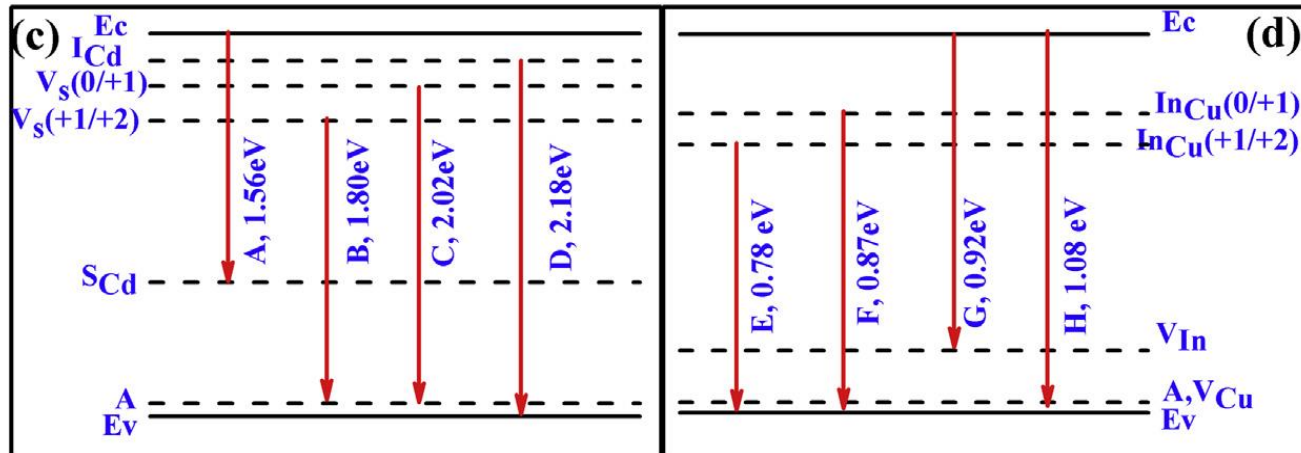
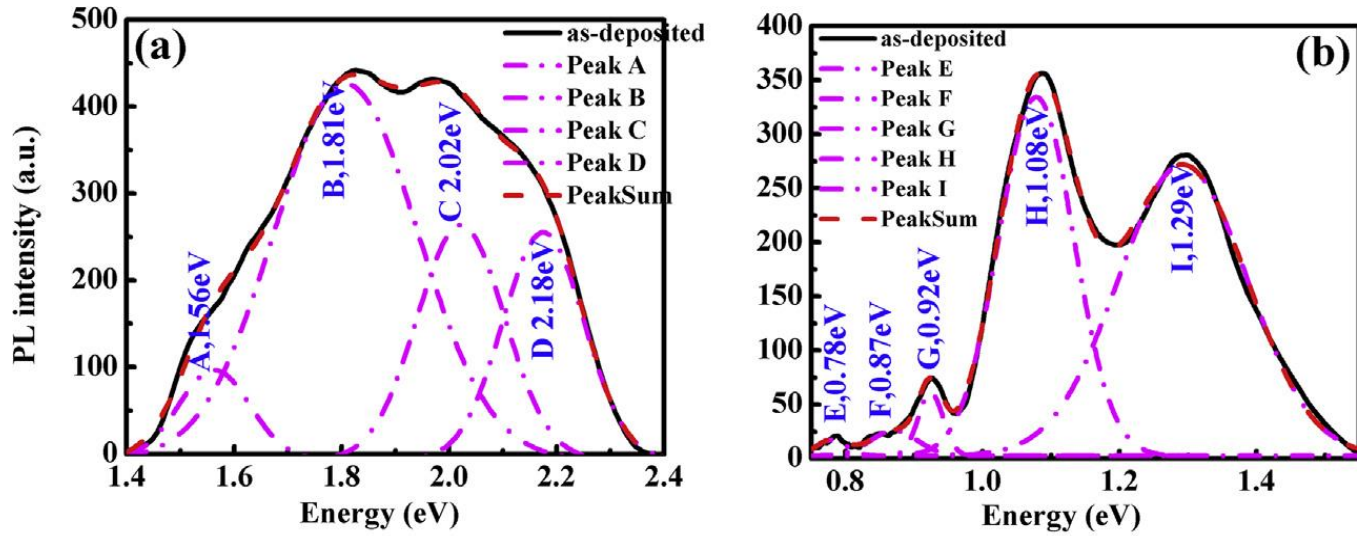
Important parameters increase up to 300 or 400 C, then decrease.

$$I_{PL}(t) = I_r(t) = \int_0^x \frac{n}{\tau_r} dx$$
$$= -S_0 \Delta n(0, t) + \int_0^x G_{ph}(x, t) - \frac{n}{\tau_{nr}} dx$$

A (diode ideality factor) could be over 2 due to tunneling enhanced process (interface state)



PL fig 1



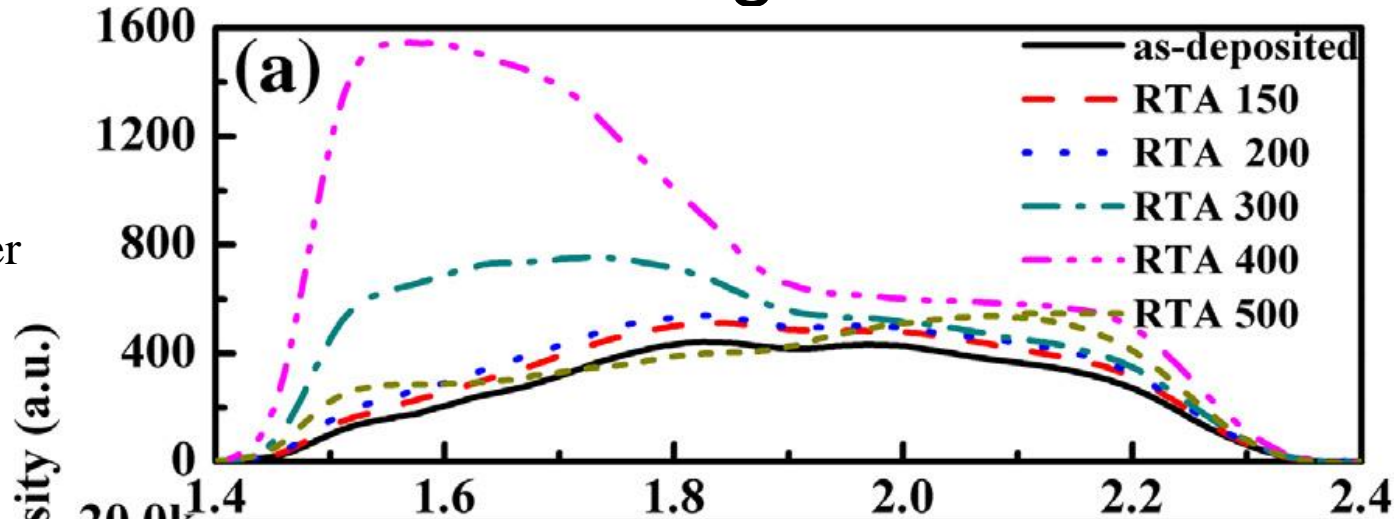
Near IR
-CIGS
absorber

Visible range
-CdS layer

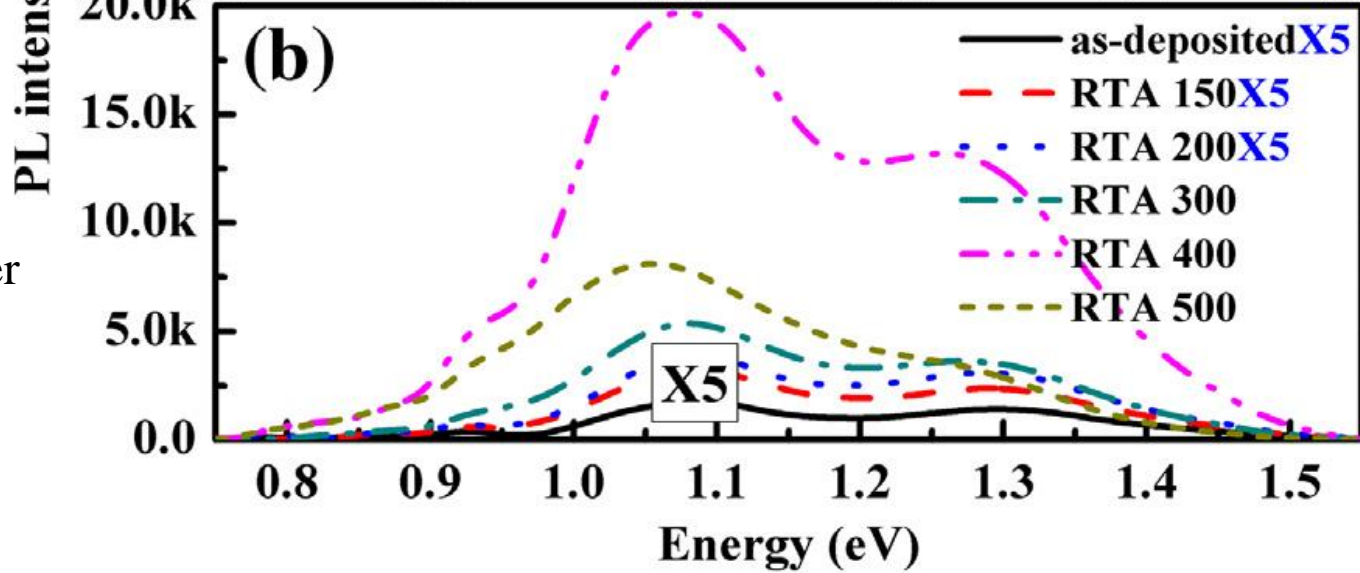


PL fig 3

CdS layer



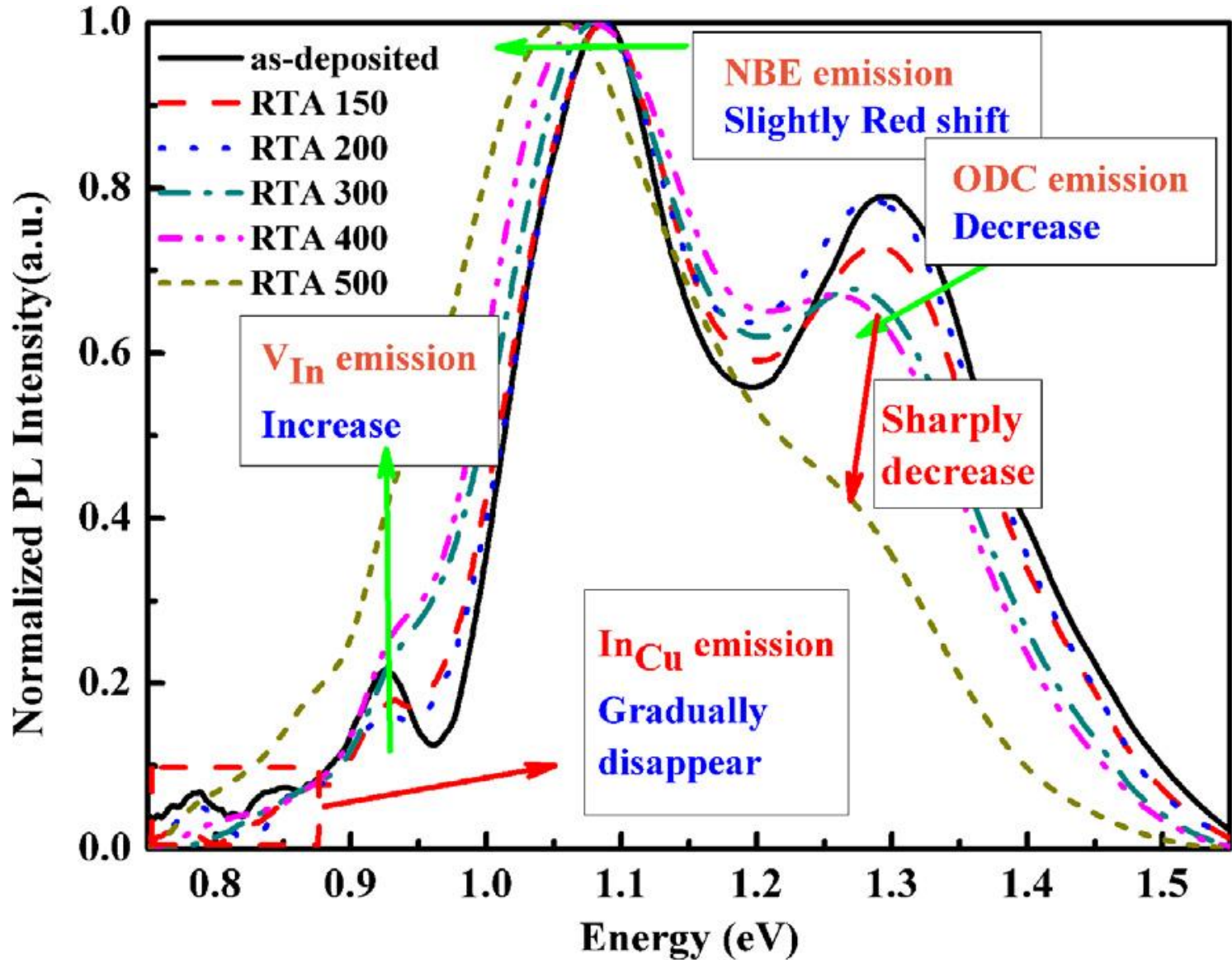
CIGS layer



PL of CIGS layer is greatly increased. CdS layer has some increase, but not nearly as much.



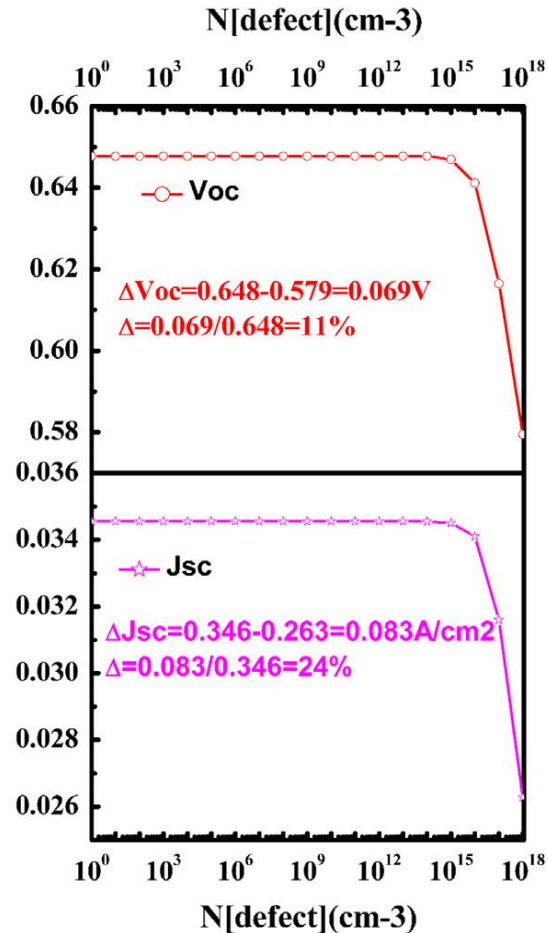
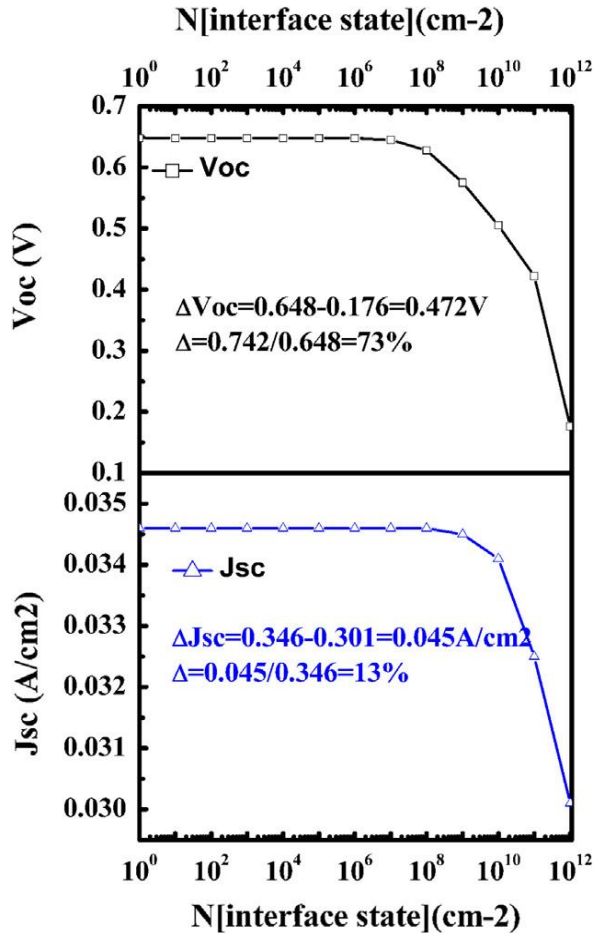
PL fig 4



No Mention of V_{Se} defect. This should probably been seen with annealing.



Simulation Results



Interface states affect mostly Voc

Defect states affect Jsc more.



J-V curve results

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Increase of both V_{oc} and J_{sc} indicates reduction of both interface and defect states.

Large drop in V_{oc} at 500C indicates major interface state formation.

Modest interdiffusion at the interface at low temperature provides beneficial effects, but large interdiffusion increases interface recombination centers.



Recombination Mechanisms

